



**THE DATASHEET OF  
NB3H83905CDR2G**



# 1.8 V/2.5 V/3.3 V Crystal Input to 1:6 LVTTL/LVCMOS Clock Fanout Buffer with OE

## NB3H83905C



### Description

The NB3H83905C is a 1.8 V, 2.5 V or 3.3 V  $V_{DD}$  core Crystal input to 1:6 LVTTL/LVCMOS fanout buffer with outputs powered by flexible 1.8 V, 2.5 V, or 3.3 V supply  $V_{DDO}$  (with  $V_{DD} \geq V_{DDO}$ ). The device accepts a fundamental Parallel Resonant crystal from 3 MHz to 40 MHz or a single-ended LVCMOS Clock from up to 100 MHz.

Two synchronous LVTTL/LVCMOS Enable lines permit independent control over outputs BCLK[0:4] and output BCLK5; enabling or disabling only when the output is in LOW state eliminating potential output glitching or runt pulse generation. When unused, leave floating open, pins will default to HIGH state.

The 6 outputs drive 50  $\Omega$  series or parallel terminated transmission lines. Parallel termination should be to 1/2  $V_{CC}$ . Series terminated lines can drive 2 loads each, or 12 lines total.

Fit, Form, and Function compatible with ICS83905 and PI6C10806.

### Features

- Six Copies of LVTTL/LVCMOS Output Clock
- Supply Operation  $V_{DD} \geq V_{DDO}$ :
  - ◆ 1.8 V  $\pm 0.2$  V, 2.5 V  $\pm 5\%$  or 3.3 V  $\pm 5\%$  Core  $V_{DD}$
  - ◆ 1.8 V  $\pm 0.2$  V, 2.5 V  $\pm 5\%$ , or 3.3 V  $\pm 5\%$  Output  $V_{DDO}$
- Crystal Oscillator Interface
- Crystal Input Frequency Range: 3 MHz to 40 MHz
- Clock Input Frequency Range: Up to 100 MHz
- LVCMOS compatible Enable Inputs
- 5 V Tolerant Enable Inputs
- Low Output to Output Skew: 80 ps Max
- Synchronous Output Enable
- Phase Noise Floor  $-160$  dBc (1 MHz)
- Industrial Temperature Range
- These are Pb-Free Devices

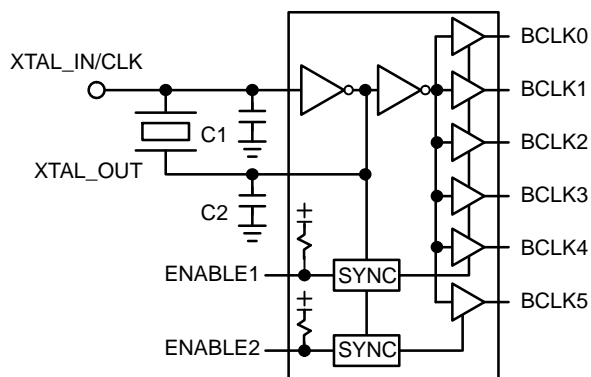
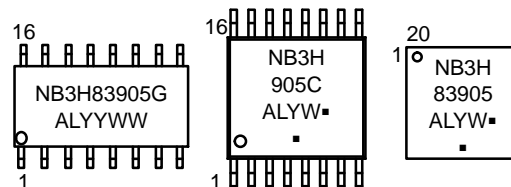


Figure 1. Simplified Block Diagram

### MARKING DIAGRAMS\*



- A = Assembly Location
- L = Wafer Lot
- YY, Y = Year
- WW, W = Work Week
- G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

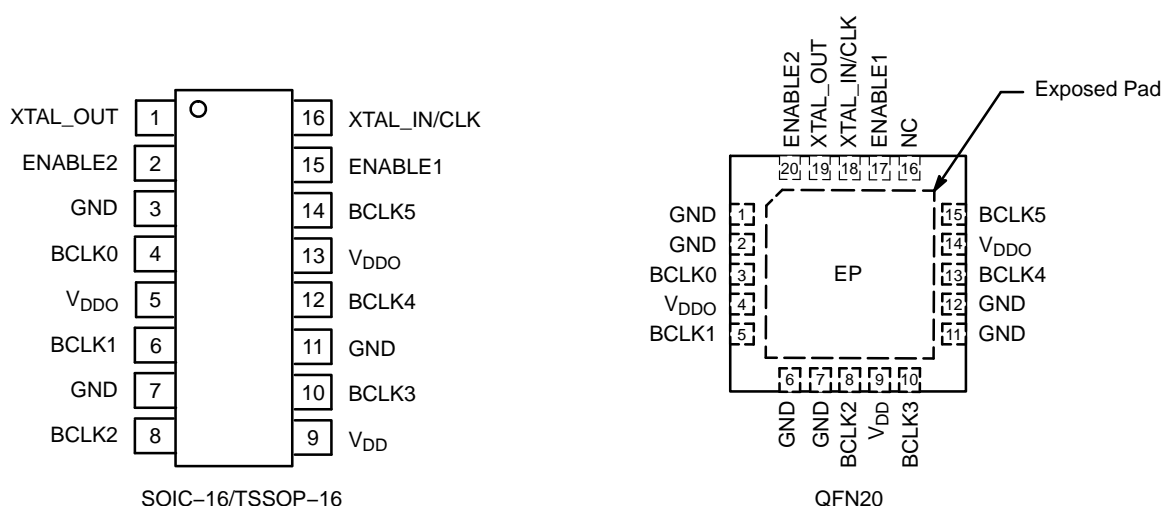
\*For additional marking information, refer to Application Note [AND8002/D](#).

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NB3H83905CDR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
NB3H83905CDTG	TSSOP-16 (Pb-Free)	96 Units / Tube
NB3H83905CDTR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel
NB3H83905CMNG	QFN-20 (Pb-Free)	92 Units / Tube

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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**Figure 2. Pinout Configuration (Top View)**

**Table 1. PIN DESCRIPTION**

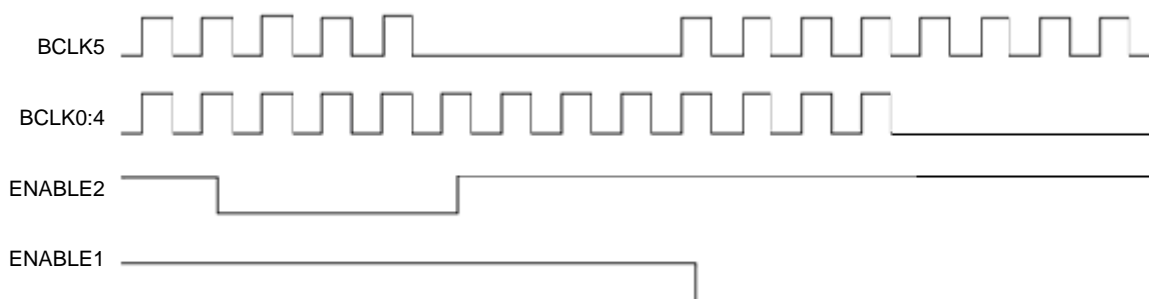
SOIC-16 / TSSOP-16	QFN-20	Name	I/O	Description
1	19	XTAL_OUT	Crystal Interface	Oscillator Output to drive Crystal
2	20	ENABLE 2	LVTTTL / LVCMOS Input	Synchronous Enable Input for BCLK5 Output. Switches only when HIGH. Open default condition HIGH due to an internal pullup resistor to V <sub>CC</sub> .
3, 7, 11	1, 2, 6, 7, 11, 12	GND	GND	GND Supply pins. All GND, V <sub>DD</sub> and V <sub>DDO</sub> pins must be externally connected to power supply to guarantee proper operation.
4, 6, 8, 10, 12, 14	3, 5, 8, 10, 13, 15	BCLK0, 1, 2, 3, 4, 5	LVCMOS Outputs	Buffered Clock Outputs
5, 13	4, 14	V <sub>DDO</sub>	POWER	Positive Supply voltage for outputs. All GND, V <sub>DD</sub> and V <sub>DDO</sub> pins must be externally connected to power supply to guarantee proper operation. Bypass with 0.01 μF cap to GND.
9	9	V <sub>DD</sub>	POWER	Positive Supply voltage for core. All GND, V <sub>DD</sub> and V <sub>DDO</sub> pins must be externally connected to power supply to guarantee proper operation. Bypass with 0.01 μF cap to GND.
-	16	NC		No Connect
15	17	ENABLE 1	LVTTTL / LVCMOS Input	Synchronous Enable Input for BCLK0/1/2/3/4 Output block. Switches only when HIGH. Open default condition HIGH due to an internal pullup resistor to V <sub>CC</sub> .
16	18	XTAL_IN/CLK	Crystal Interface	Oscillator Input from Crystal. Single ended Clock Input.
-	EP		-	The Exposed Pad (EP) on the QFN-20 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat-sinking conduit. The pad is not electrically connected to the die, but is recommended to be electrically and thermally connected to GND on the PC board.

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**Table 2. CLOCK ENABLE FUNCTION TABLE**

Control Inputs		Outputs	
ENABLE1*	ENABLE2*	BCLK0:BCLK4	BCLK5
0	0	LOW	LOW
0	1	LOW	Toggling
1	0	Toggling	LOW
1	1	Toggling	Toggling

\*Defaults HIGH when floating open.



**Figure 3. ENABLEx Control Timing Diagram**

The ENABLEx control inputs will synchronously enable or disable the selected output(s). This control detects the falling edge of the internal signal and asserts or de-asserts the output after 3 clock cycles. When ENABLEx is LOW, the outputs are disabled to a LOW state. When ENABLEx is HIGH, the outputs are enabled to toggle.

**Table 3. RECOMMENDED CRYSTAL PARAMETERS**

Crystal	Fundamental AT-Cut
Frequency	10 to 40 MHz
Load Capacitance*	16–20 pF
Shunt Capacitance, C0	7 pF Max
Equivalent Series Resistance	50 Ω Max
Drive Level	1 mW

\*See APPLICATION INFORMATION; Crystal Input Interface for CL loading

**Table 4. ATTRIBUTES** (Note 1)

Characteristics	Value
ESD Protection Human Body Model Machine Model	> 2 kV > 200 V
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Level 1
Flammability Rating Oxygen Index	UL-94 code V-0 A 1/8" 28 to 34
Transistor Count	213 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional information, see Application Note [AND8003/D](#).

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**Table 5. MAXIMUM RATINGS** (Note 2)

Symbol	Parameter	Condition 1	Condition 1	Rating	Unit
$V_{DDx}$	Positive Power Supply	GND = 0 V		4.6	V
$V_I$	Input Voltage			$-0.5 \leq V_I \leq V_{DD} + 0.5$	V
$T_A$	Operating Temperature Range, Industrial			-40 to $\leq$ +85	°C
$T_{stg}$	Storage Temperature Range			-65 to +150	°C
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-16 SOIC-16	80 55	°C/W
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	(Note 3)	SOIC-16	33-36	°C/W
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-16 TSSOP-16	138 108	°C/W
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	(Note 3)	TSSOP-16	33-36	°C/W
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	QFN-20 QFN-20	47 33	°C/W
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	(Note 3)	QFN-20	18	°C/W
$T_{sol}$	Wave Solder	3 sec @ 248°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

2. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and not valid simultaneously. If stress limits are exceeded device functional operation is not implied, damage may occur and reliability may be affected.
3. JEDEC standard multilayer board – 2S2P (2 signal, 2 power).

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**Table 6. DC CHARACTERISTICS**

Symbol	Characteristic	Min	Typ	Max	Unit
<b><math>V_{DD} = V_{DDO} = 3.135 \text{ V to } 3.465 \text{ V (3.3 V } \pm 5\%); \text{ GND} = 0 \text{ V, } T_A = -40^\circ\text{C to } +85^\circ\text{C}</math></b>					
IDD	Core Quiescent Power Supply Current (ENABLEx = LOW)	–	–	10	mA
IDDO	Output Quiescent Power Supply Current (ENABLEx = LOW)	–	–	5	mA
V <sub>IH</sub>	Input HIGH Voltage ENABLEx, XTAL_IN/CLK	2	–	V <sub>DD</sub> + 0.3 V	V
V <sub>IL</sub>	Input LOW Voltage ENABLEx, XTAL_IN/CLK	–0.3	–	0.8	V
V <sub>OH</sub>	Output HIGH Voltage (Note 4)	2.6	–	–	V
V <sub>OL</sub>	Output LOW Voltage (Note 4)	–	–	0.5	V
C <sub>IN</sub>	Input Capacitance	–	4	–	pF
C <sub>PD</sub>	Power Dissipation Capacitance (per Output) (Note 4)	–	19	–	pF
R <sub>OUT</sub>	Output Impedance (Note 4)	–	7	–	Ω
<b><math>V_{DD} = V_{DDO} = 2.375 \text{ V to } 2.625 \text{ V (2.5 V } \pm 5\%); \text{ GND} = 0 \text{ V, } T_A = -40^\circ\text{C to } +85^\circ\text{C}</math></b>					
IDD	Core Quiescent Power Supply Current (ENABLEx = LOW)	–	–	8	mA
IDDO	Output Quiescent Power Supply Current (ENABLEx = LOW)	–	–	4	mA
V <sub>IH</sub>	Input HIGH Voltage ENABLEx, XTAL_IN/CLK	1.7	–	V <sub>DD</sub> + 0.3 V	V
V <sub>IL</sub>	Input LOW Voltage ENABLEx, XTAL_IN/CLK	–0.3	–	0.7	V
V <sub>OH</sub>	Output HIGH Voltage (I <sub>OH</sub> = –1 mA) Output HIGH Voltage (Note 4)	2.0 1.8	– –	– –	V
V <sub>OL</sub>	Output LOW Voltage (I <sub>OL</sub> = 1 mA) Output LOW Voltage (Note 4)	– –	– –	0.4 0.45	V
C <sub>IN</sub>	Input Capacitance	–	4	–	pF
C <sub>PD</sub>	Power Dissipation Capacitance (per Output) (Note 4)	–	18	–	pF
R <sub>OUT</sub>	Output Impedance (Note 4)	–	7	–	Ω
<b><math>V_{DD} = V_{DDO} = 1.6 \text{ V to } 2.0 \text{ V (1.8 V } \pm 0.2 \text{ V}); \text{ GND} = 0 \text{ V, } T_A = -40^\circ\text{C to } +85^\circ\text{C}</math></b>					
IDD	Core Quiescent Power Supply Current (ENABLEx = LOW)	–	–	5	mA
IDDO	Output Quiescent Power Supply Current (ENABLEx = LOW)	–	–	3	mA
V <sub>IH</sub>	Input HIGH Voltage ENABLEx, XTAL_IN/CLK	0.65 * V <sub>DD</sub>	–	V <sub>DD</sub> + 0.3 V	V
V <sub>IL</sub>	Input LOW Voltage ENABLEx, XTAL_IN/CLK	–0.3	–	0.35 * V <sub>DD</sub>	V
V <sub>OH</sub>	Output HIGH Voltage (Note 4)	V <sub>DDO</sub> – 0.3	–	–	V
V <sub>OL</sub>	Output LOW Voltage (Note 4)	–	–	0.35	V
C <sub>IN</sub>	Input Capacitance	–	4	–	pF
C <sub>PD</sub>	Power Dissipation Capacitance (per Output) (Note 4)	–	16	–	pF
R <sub>OUT</sub>	Output Impedance (Note 4)	–	10	–	Ω

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

4. Parallel terminated 50 Ω to V<sub>DDO</sub>/2 (see Figure 5).

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**Table 6. DC CHARACTERISTICS** (continued)

Symbol	Characteristic	Min	Typ	Max	Unit
<b><math>V_{DD} = 3.135\text{ V to }3.465\text{ V (}3.3\text{ V } \pm 5\%); V_{DDO} = 2.375\text{ V to }2.625\text{ V (}2.5\text{ V } \pm 5\%); GND = 0\text{ V, }T_A = -40^\circ\text{C to }+85^\circ\text{C}</math></b>					
IDD	Core Quiescent Power Supply Current (ENABLEx = LOW)	–	–	10	mA
IDDO	Output Quiescent Power Supply Current (ENABLEx = LOW)	–	–	4	mA
V <sub>IH</sub>	Input HIGH Voltage ENABLEx, XTAL_IN/CLK	2	–	V <sub>DD</sub> + 0.3 V	V
V <sub>IL</sub>	Input LOW Voltage ENABLEx, XTAL_IN/CLK	–0.3	–	0.8	V
V <sub>OH</sub>	Output HIGH Voltage (I <sub>OH</sub> = –1 mA) Output HIGH Voltage (Note 4)	2.0 1.8	– –	– –	V
V <sub>OL</sub>	Output LOW Voltage (I <sub>OL</sub> = 1 mA) Output LOW Voltage (Note 4)	– –	– –	0.4 0.45	V
C <sub>IN</sub>	Input Capacitance	–	4	–	pF
C <sub>PD</sub>	Power Dissipation Capacitance (per Output) (Note 4)	–	18	–	pF
R <sub>OUT</sub>	Output Impedance (Note 4)	–	7	–	Ω

**$V_{DD} = 3.135\text{ V to }3.465\text{ V (}3.3\text{ V } \pm 5\%); V_{DDO} = 1.6\text{ V to }2.0\text{ V (}1.8\text{ V } \pm 0.2\text{ V)}; GND = 0\text{ V, }T_A = -40^\circ\text{C to }+85^\circ\text{C}$**

IDD	Core Quiescent Power Supply Current (ENABLEx = LOW)	–	–	10	mA
IDDO	Output Quiescent Power Supply Current (ENABLEx = LOW)	–	–	3	mA
V <sub>IH</sub>	Input HIGH Voltage ENABLEx, XTAL_IN/CLK	2	–	V <sub>DD</sub> + 0.3 V	V
V <sub>IL</sub>	Input LOW Voltage ENABLEx, XTAL_IN/CLK	–0.3	–	0.8	V
V <sub>OH</sub>	Output HIGH Voltage (Note 4)	V <sub>DDO</sub> – 0.3	–	–	V
V <sub>OL</sub>	Output LOW Voltage (Note 4)	–	–	0.35	V
C <sub>IN</sub>	Input Capacitance	–	4	–	pF
C <sub>PD</sub>	Power Dissipation Capacitance (per Output) (Note 4)	–	16	–	pF
R <sub>OUT</sub>	Output Impedance (Note 4)	–	10	–	Ω

**$V_{DD} = 2.375\text{ V to }2.625\text{ V (}2.5\text{ V } \pm 5\%); V_{DDO} = 1.6\text{ V to }2.0\text{ V (}1.8\text{ V } \pm 0.2\text{ V)}; GND = 0\text{ V, }T_A = -40^\circ\text{C to }+85^\circ\text{C}$**

IDD	Core Quiescent Power Supply Current (ENABLEx = LOW)	–	–	8	mA
IDDO	Output Quiescent Power Supply Current (ENABLEx = LOW)	–	–	3	mA
V <sub>IH</sub>	Input HIGH Voltage ENABLEx, XTAL_IN/CLK	1.7	–	V <sub>DD</sub> + 0.3 V	V
V <sub>IL</sub>	Input LOW Voltage ENABLEx, XTAL_IN/CLK	–0.3	–	0.7	V
V <sub>OH</sub>	Output HIGH Voltage (Note 4)	V <sub>DDO</sub> – 0.3	–	–	V
V <sub>OL</sub>	Output LOW Voltage (Note 4)	–	–	0.35	V
C <sub>IN</sub>	Input Capacitance	–	4	–	pF
C <sub>PD</sub>	Power Dissipation Capacitance (per Output) (Note 4)	–	16	–	pF
R <sub>OUT</sub>	Output Impedance (Note 4)	–	10	–	Ω

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

4. Parallel terminated 50 Ω to V<sub>DDO</sub>/2 (see Figure 5).

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**Table 7. AC CHARACTERISTICS**

Symbol	Characteristic	Min	Typ	Max	Unit	
<b><math>V_{DD} = V_{DDO} = 3.135\text{ V to }3.465\text{ V (3.3 V } \pm 5\%); GND = 0\text{ V, }T_A = -40^\circ\text{C to }+85^\circ\text{C (Note 5)}</math></b>						
$F_{max}$	Input Frequency Crystal	3	-	40	MHz	
	Input Frequency Clock (XTAL_IN/CLK)	DC	-	100		
$t_{EN} / t_{DIS}$	Delay for Output Enable / Disable Time ENABLEx to BCLKn	-	-	4	Cycles	
$tSKEW_{DC}$	Duty Cycle Skew (See Figure 4)	48	-	52	%	
$tSKEW_{O-O}$	Output to Output Skew Within A Device (Same Conditions)	0	50	80	ps	
$\Phi_{NOISE}$	Phase-Noise Performance $f_{out} = 25\text{ MHz}$	100 Hz off Carrier	-	-123	-	dBc/Hz
		1 kHz off Carrier	-	-142	-	
		10 kHz off Carrier	-	-153	-	
		100 kHz off Carrier	-	-164	-	
$t_{JIT}(\Phi)$	RMS Phase Jitter	25 MHz carrier, Integration Range 12 kHz to 20 MHz	-	0.08	-	ps
		25 MHz carrier, Integration Range 100 Hz to 1 MHz	-	0.08	-	
tr/tf	Output Rise and Fall Times (20%; 80%)	200	-	800	ps	

**$V_{DD} = V_{DDO} = 2.375\text{ V to }2.625\text{ V (2.5 V } \pm 5\%); GND = 0\text{ V, }T_A = -40^\circ\text{C to }+85^\circ\text{C (Note 5)}$**

$F_{max}$	Input Frequency Crystal	3	-	40	MHz	
	Input Frequency Clock (XTAL1)	DC	-	100		
$t_{EN} / t_{DIS}$	Delay for Output Enable / Disable Time ENABLEx to BCLKn	-	-	4	Cycles	
$tSKEW_{DC}$	Duty Cycle Skew (See Figure 4)	47	-	53	%	
$tSKEW_{O-O}$	Output to Output Skew Within A Device (Same Conditions)	0	50	80	ps	
$\Phi_{NOISE}$	Phase-Noise Performance $f_{out} = 25\text{ MHz}$	100 Hz off Carrier	-	-118	-	dBc/Hz
		1 kHz off Carrier	-	-137	-	
		10 kHz off Carrier	-	-151	-	
		100 kHz off Carrier	-	-165	-	
$t_{JIT}(\Phi)$	RMS Phase Jitter	25 MHz carrier, Integration Range 12 kHz to 20 MHz	-	0.13	-	ps
		25 MHz carrier, Integration Range 100 Hz to 1 MHz	-	0.13	-	
tr/tf	Output Rise and Fall Times (20%; 80%)	200	-	800	ps	

**$V_{DD} = V_{DDO} = 1.6\text{ V to }2.0\text{ V (1.8 V } \pm 0.2\text{ V); GND = 0 V, }T_A = -40^\circ\text{C to }+85^\circ\text{C (Note 5)}$**

$F_{max}$	Input Frequency Crystal	3	-	40	MHz	
	Input Frequency Clock (XTAL1)	DC	-	100		
$t_{EN} / t_{DIS}$	Delay for Output Enable / Disable Time ENABLEx to BCLKn	-	-	4	Cycles	
$tSKEW_{DC}$	Duty Cycle Skew (See Figure 4)	47	-	53	%	
$tSKEW_{O-O}$	Output to Output Skew Within A Device (Same Conditions)	0	50	80	ps	
$\Phi_{NOISE}$	Phase-Noise Performance $f_{out} = 25\text{ MHz}$	100 Hz off Carrier	-	-129	-	dBc/Hz
		1 kHz off Carrier	-	-145	-	
		10 kHz off Carrier	-	-147	-	
		100 kHz off Carrier	-	-157	-	
$t_{JIT}(\Phi)$	RMS Phase Jitter	25 MHz carrier, Integration Range 12 kHz to 20 MHz	-	0.27	-	ps
		25 MHz carrier, Integration Range 100 Hz to 1 MHz	-	0.27	-	
tr/tf	Output Rise and Fall Times (20%; 80%)	200	-	900	ps	

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

5. Crystal inputs  $\leq F_{max}$ . Outputs loaded with  $50\ \Omega$  to  $V_{DDO}/2$ . CLOCK (LVCMOS levels at XTAL1 input) 50% duty cycle. See Figures 4 and 7. See APPLICATION INFORMATION; Crystal Input Interface for CL loading.

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**Table 7. AC CHARACTERISTICS** (continued)

Symbol	Characteristic	Min	Typ	Max	Unit	
<b>V<sub>DD</sub> = 3.135 V to 3.465 V (3.3 V ±5%); V<sub>DDO</sub> = 2.375 V to 2.625 V (2.5 V ±5%); GND = 0 V, T<sub>A</sub> = -40°C to +85°C (Note 5)</b>						
F <sub>max</sub>	Input Frequency Crystal	3	-	40	MHz	
	Input Frequency Clock (XTAL_IN/CLK)	DC	-	100		
t <sub>EN</sub> / t <sub>DIS</sub>	Delay for Output Enable / Disable Time ENABLEx to BCLKn	-	-	4	Cycles	
tSKEW <sub>DC</sub>	Duty Cycle Skew (See Figure 4)	48	-	52	%	
tSKEW <sub>O-O</sub>	Output to Output Skew Within A Device (Same Conditions)	0	50	80	ps	
ΦNOISE	Phase-Noise Performance f <sub>out</sub> = 25 MHz	100 Hz off Carrier	-	-129	-	dBc/Hz
		1 kHz off Carrier	-	-145	-	
		10 kHz off Carrier	-	-147	-	
		100 kHz off Carrier	-	-157	-	
tJIT(Φ)	RMS Phase Jitter	25 MHz carrier, Integration Range 12 kHz to 20 MHz	-	0.14	-	ps
		25 MHz carrier, Integration Range 100 Hz to 1 MHz	-	0.14	-	
tr/tf	Output Rise and Fall Times (20%; 80%)	200	-	800	ps	

**V<sub>DD</sub> = 3.135 V to 3.465 V (3.3 V ±5%); V<sub>DDO</sub> = 1.6 V to 2.0 V (1.8 V ±0.2 V); GND = 0 V, T<sub>A</sub> = -40°C to +85°C (Note 5)**

F <sub>max</sub>	Input Frequency Crystal	3	-	40	MHz	
	Input Frequency Clock (XTAL1)	DC	-	100		
t <sub>EN</sub> / t <sub>DIS</sub>	Delay for Output Enable / Disable Time ENABLEx to BCLKn	-	-	4	Cycles	
tSKEW <sub>DC</sub>	Duty Cycle Skew (See Figure 4)	48	-	52	%	
tSKEW <sub>O-O</sub>	Output to Output Skew Within A Device (Same Conditions)	0	50	80	ps	
ΦNOISE	Phase-Noise Performance f <sub>out</sub> = 25 MHz	100 Hz off Carrier	-	-129	-	dBc/Hz
		1 kHz off Carrier	-	-145	-	
		10 kHz off Carrier	-	-147	-	
		100 kHz off Carrier	-	-157	-	
tJIT(Φ)	RMS Phase Jitter	25 MHz carrier, Integration Range 12 kHz to 20 MHz	-	0.18	-	ps
		25 MHz carrier, Integration Range 100 Hz to 1 MHz	-	0.18	-	
tr/tf	Output Rise and Fall Times (20%; 80%)	200	-	900	ps	

**V<sub>DD</sub> = 2.375 V to 2.625 V (2.5 V ±5%); V<sub>DDO</sub> = 1.6 V to 2.0 V (1.8 V ±0.2 V); GND = 0 V, T<sub>A</sub> = -40°C to +85°C (Note 5)**

F <sub>max</sub>	Input Frequency Crystal	3	-	40	MHz	
	Input Frequency Clock (XTAL1)	DC	-	100		
t <sub>EN</sub> / t <sub>DIS</sub>	Delay for Output Enable / Disable Time ENABLEx to BCLKn	-	-	4	Cycles	
tSKEW <sub>DC</sub>	Duty Cycle Skew (See Figure 4)	47	-	53	%	
tSKEW <sub>O-O</sub>	Output to Output Skew Within A Device (Same Conditions)	0	50	80	ps	
ΦNOISE	Phase-Noise Performance f <sub>out</sub> = 25 MHz/	100 Hz off Carrier	-	-129	-	dBc/Hz
		1 kHz off Carrier	-	-145	-	
		10 kHz off Carrier	-	-147	-	
		100 kHz off Carrier	-	-157	-	
tJIT(Φ)	RMS Phase Jitter	25 MHz carrier, Integration Range 12 kHz to 20 MHz	-	0.19	-	ps
		25 MHz carrier, Integration Range 100 Hz to 1 MHz	-	0.19	-	
tr/tf	Output Rise and Fall Times (20%; 80%)	200	-	900	ps	

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

5. Crystal inputs ≤ F<sub>max</sub>. Outputs loaded with 50 Ω to V<sub>DDO</sub>/2. CLOCK (LVCMOS levels at XTAL1 input) 50% duty cycle. See Figures 4 and 7. See APPLICATION INFORMATION; Crystal Input Interface for CL loading.

# NB3H83905C

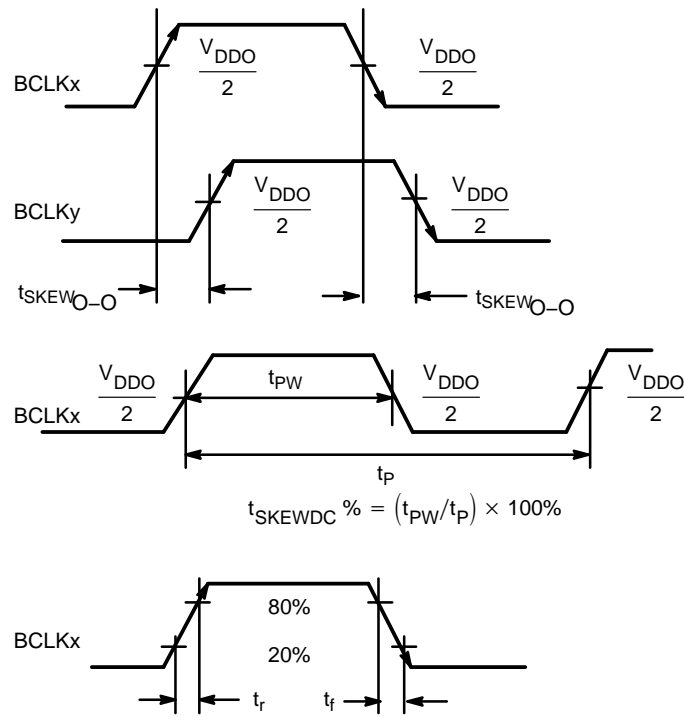


Figure 4. AC Reference Measurement

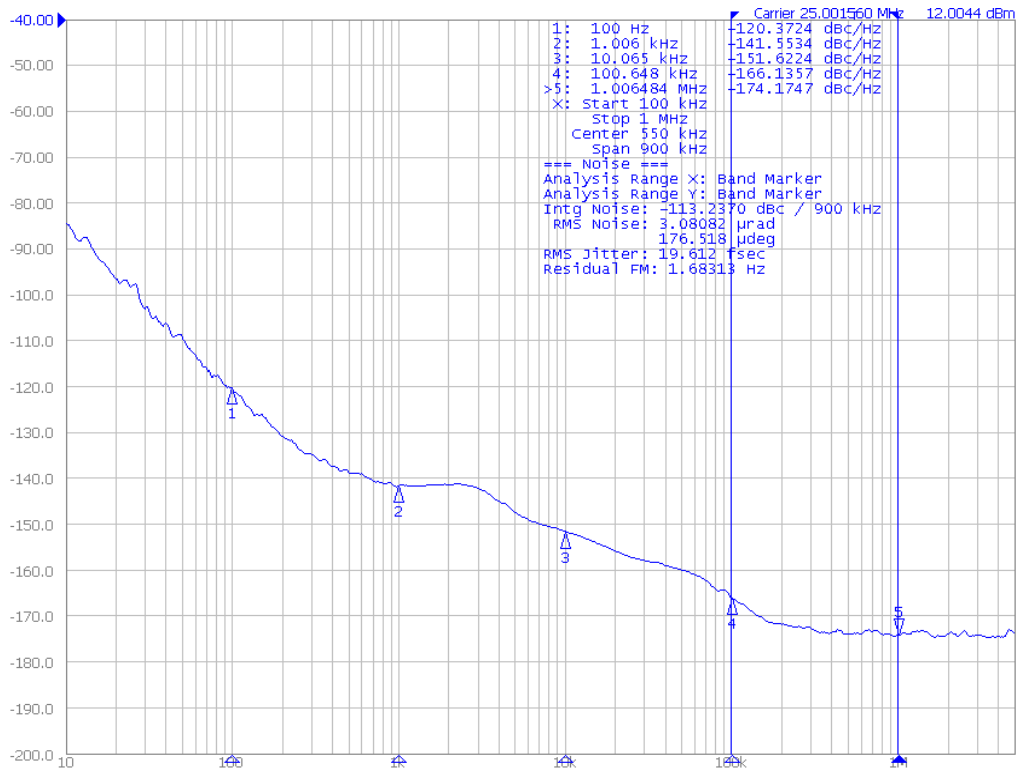


Figure 5. Typical Phase Noise Plot of the NB3H83905C Operating at 25 MHz  $V_{DD} = V_{DDO} = 3.3$  V

# NB3H83905C

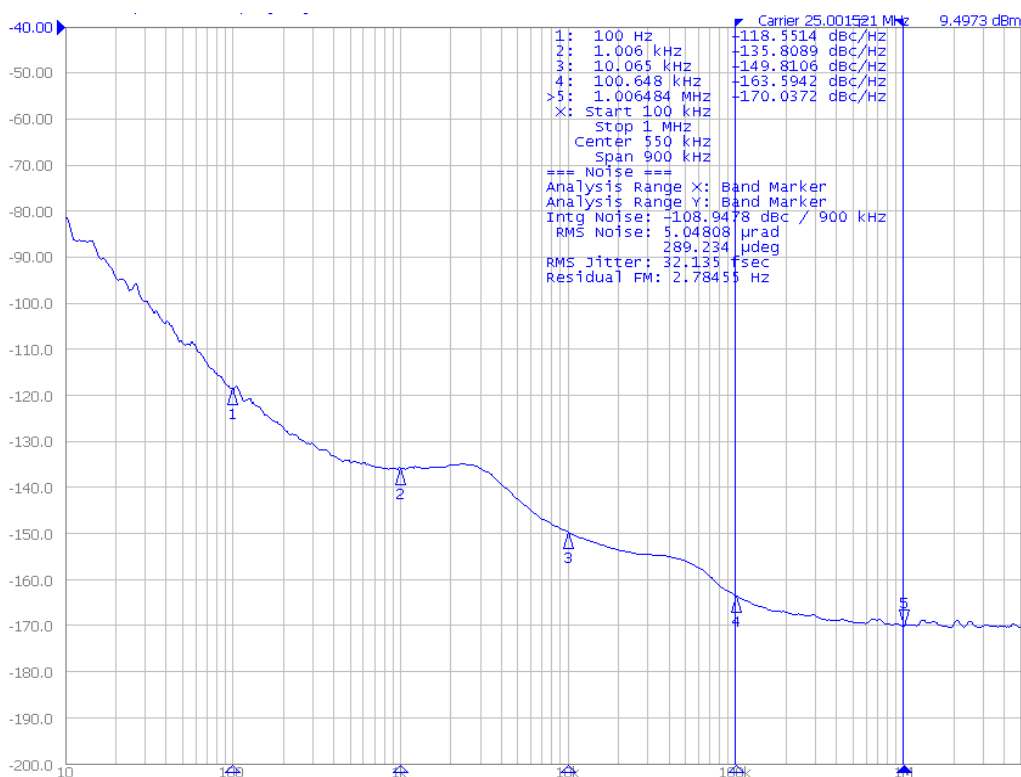


Figure 6. Typical Phase Noise Plot of the NB3H83905C Operating at 25 MHz  $V_{DD} = V_{DDO} = 2.5$  V

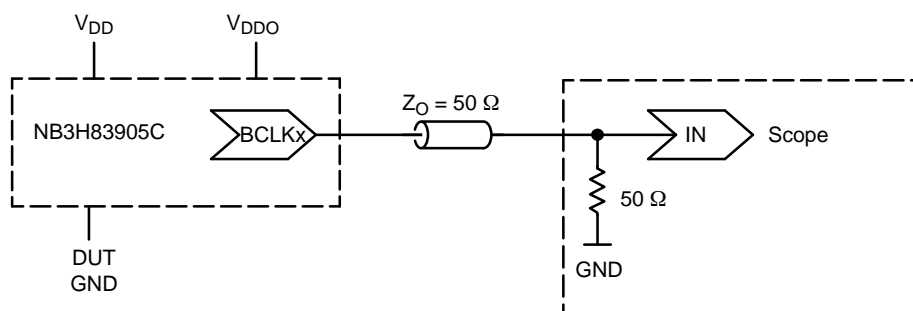


Figure 7. Typical Device Evaluation and Termination Setup – See Table 8

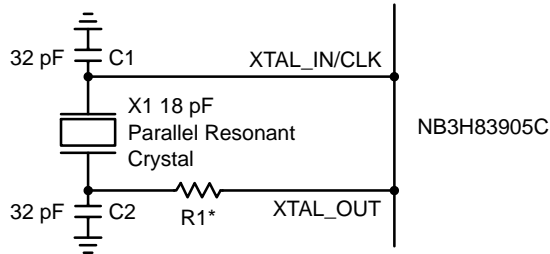
Table 8. TEST SUPPLY SETUP.  $V_{DDO}$  SUPPLY MAY BE CENTERED ON 0.0 V (SCOPE GND) TO PERMIT DIRECT CONNECTION INTO “50 Ω TO GND” SCOPE MODULE.  $V_{DD}$  SUPPLY TRACKS DUT GND PIN

Spec Condition:	Test Setup $V_{DD}$ :	Test Setup $V_{DDO}$ :	Test Setup DUT GND:
$V_{DD} = V_{DDO} = 3.135$ V to $3.465$ V ( $3.3$ V $\pm 5\%$ )	1.56 to 1.73 V	1.56 to 1.73 V	-1.56 to -1.73 V
$V_{DD} = V_{DDO} = 2.375$ V to $2.625$ V ( $2.5$ V $\pm 5\%$ )	1.1875 to 1.3125 V	1.1875 to 1.3125 V	-1.1875 to -1.3125 V
$V_{DD} = V_{DDO} = 1.6$ V to $2.0$ V ( $1.8$ V $\pm 0.2$ V)	0.8 to 1.0 V	0.8 to 1.0 V	-0.8 to -1.0 V
$V_{DD} = 3.135$ V to $3.465$ V ( $3.3$ V $\pm 5\%$ ); $V_{DDO} = 2.375$ V to $2.625$ V ( $2.5$ V $\pm 5\%$ )	1.955 to 2.1525 V	1.1875 to 1.3125 V	-1.1875 to -1.3125 V
$V_{DD} = 3.135$ V to $3.465$ V ( $3.3$ V $\pm 5\%$ ); $V_{DDO} = 1.6$ V to $2.0$ V ( $1.8$ V $\pm 0.2$ V)	2.335 to 2.465 V	0.8 to 1.0 V	-0.8 to -1.0 V
$V_{DD} = 2.375$ V to $2.625$ V ( $2.5$ V $\pm 5\%$ ); $V_{DDO} = 1.6$ V to $2.0$ V ( $1.8$ V $\pm 0.2$ V)	1.575 to 1.625 V	0.8 to 1.0 V	-0.8 to -1.0 V

APPLICATION INFORMATION

**Crystal Input Interface**

Figure 8 shows the NB3H83905C device crystal oscillator interface using a typical parallel resonant crystal. A parallel crystal with loading capacitance  $C_L = 18 \text{ pF}$  would use  $C1 = 32 \text{ pF}$  and  $C2 = 32 \text{ pF}$  as nominal values, assuming  $4 \text{ pF}$  of stray cap per line. The frequency accuracy and duty cycle skew can be fine tuned by adjusting the  $C1$  and  $C2$  values. For example, increasing the  $C1$  and  $C2$  values will reduce the operational frequency. Note  $R1$  is optional and may be  $0 \Omega$ .



**Figure 8. NB3H83905C Crystal Oscillator Interface**  
\* R1 is optional

**Termination**

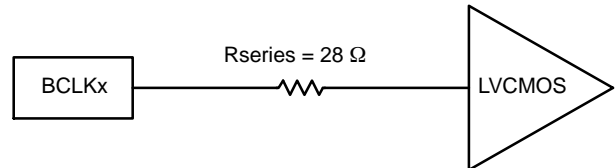
NB3H83905C device output series termination may be used by locating a  $28 \Omega$  series resistor at the driver pin as shown in Figure 9. Alternatively, a Thevenin Parallel termination may be used by locating a  $100 \Omega$  pullup resistor to  $V_{DD}$  and a  $100 \Omega$  pullup resistor to GND at the receiver pin, instead of an  $R_s$  source termination resistor, Figure 10.

**Unused Input and Output Pins**

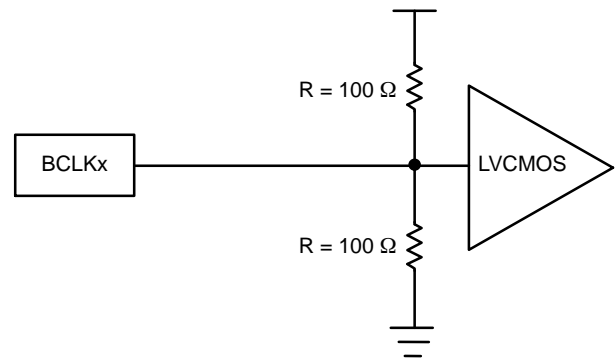
All LVCMOS control pins have internal pull-ups or pull-downs; additional external resistors are not required (optionally  $1 \text{ k}\Omega$  resistors may be used). All unused LVCMOS outputs can be left floating with no trace attached.

**Bypass**

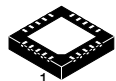
The  $V_{DD}$  and  $V_{DDO}$  supply pins should be bypassed with both a  $10 \mu\text{F}$  and a  $0.1 \mu\text{F}$  cap from supply pins to GND.



**Figure 9. Series Termination**



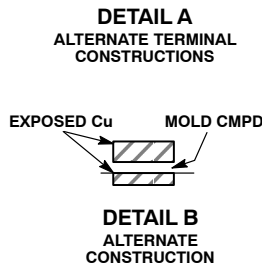
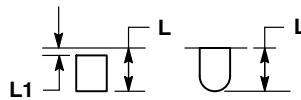
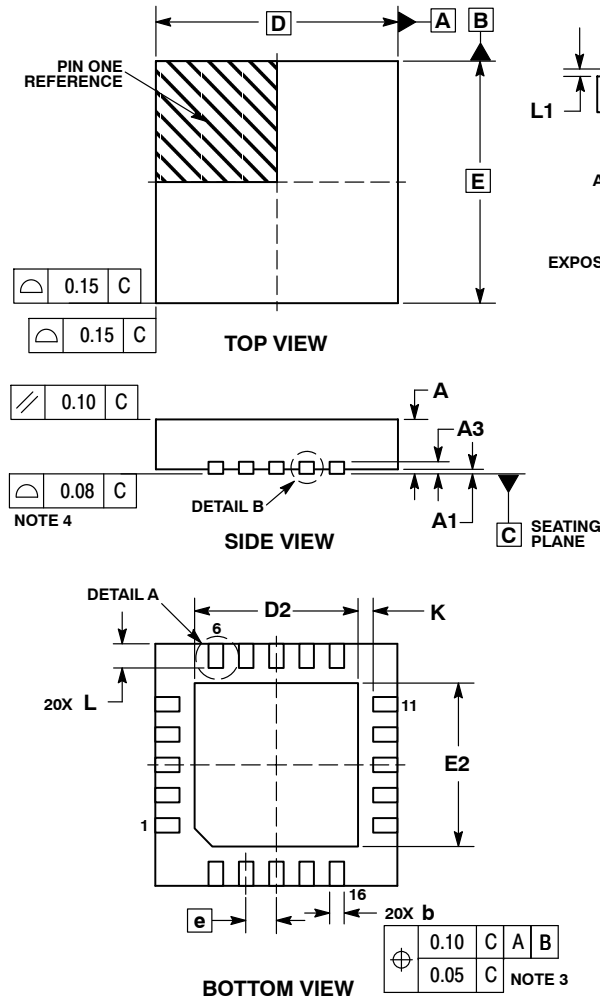
**Figure 10. Optional Thevenin Termination**



SCALE 2:1

QFN20 4x4, 0.5P  
CASE 485BH  
ISSUE O

DATE 19 FEB 2010

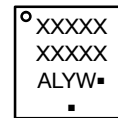


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20	REF
b	0.20	0.30
D	4.00	BSC
D2	2.60	2.80
E	4.00	BSC
E2	2.60	2.80
e	0.50	BSC
K	0.20	---
L	0.35	0.45
L1	0.00	0.15

GENERIC MARKING DIAGRAM\*

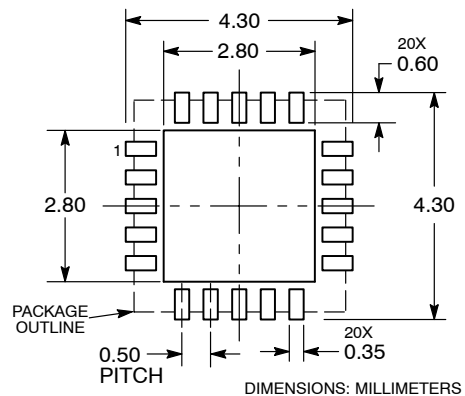


- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

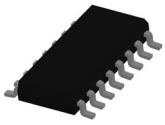
\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

MOUNTING FOOTPRINT



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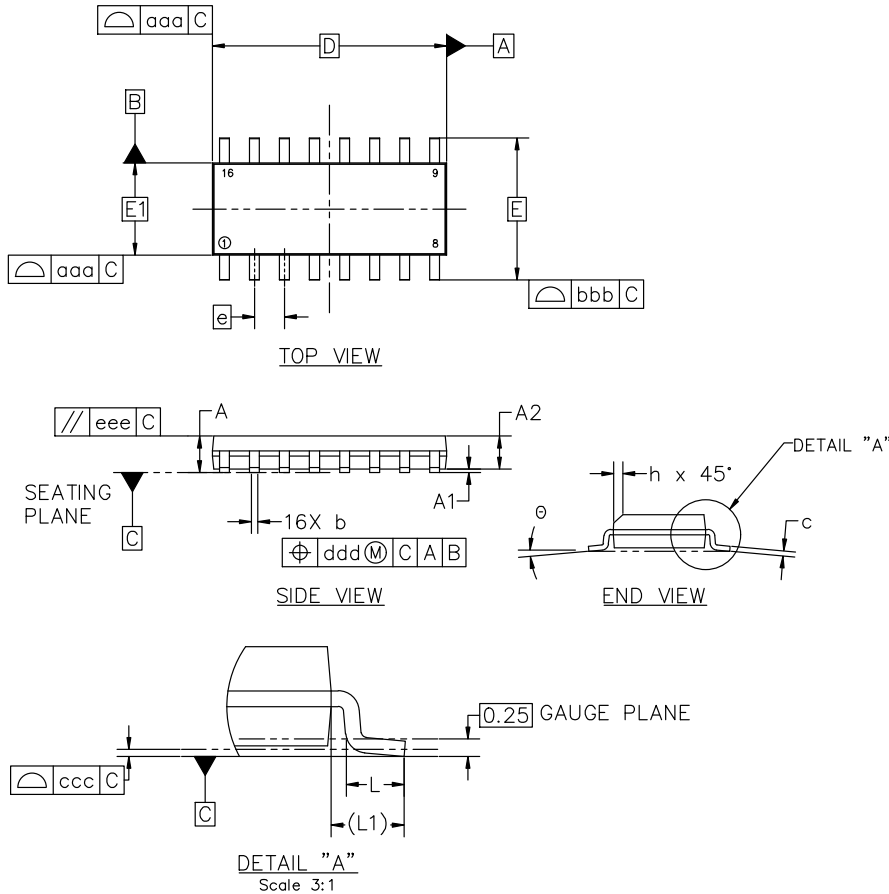


**SOIC-16 9.90x3.90x1.37 1.27P**  
**CASE 751B**  
**ISSUE M**

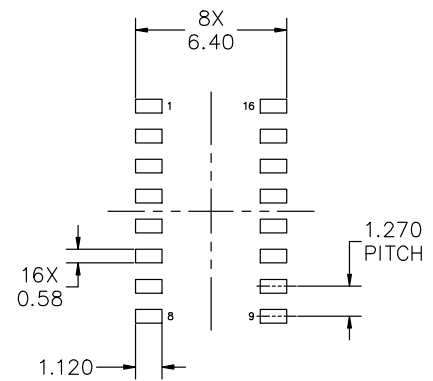
DATE 18 OCT 2024

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. DIMENSION IN MILLIMETERS. ANGLE IN DEGREES.
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15mm PER SIDE.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127mm TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.



MILLIMETERS			
DIM	MIN	NOM	MAX
A	1.35	1.55	1.75
A1	0.10	0.18	0.25
A2	1.25	1.37	1.50
b	0.35	0.42	0.49
c	0.19	0.22	0.25
D	9.90 BSC		
E	6.00 BSC		
E1	3.90 BSC		
e	1.27 BSC		
h	0.25	---	0.50
L	0.40	0.83	1.25
L1	1.05 REF		
θ	0°	---	7°
TOLERANCE OF FORM AND POSITION			
aaa	0.10		
bbb	0.20		
ccc	0.10		
ddd	0.25		
eee	0.10		



RECOMMENDED MOUNTING FOOTPRINT

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE onsemi SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D

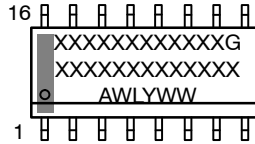
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**SOIC-16 9.90x3.90x1.37 1.27P**  
**CASE 751B**  
**ISSUE M**

DATE 18 OCT 2024

**GENERIC  
MARKING DIAGRAM\***



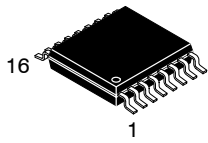
XXXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

<p><b>STYLE 1:</b></p> <p>PIN 1. COLLECTOR  2. BASE  3. EMITTER  4. NO CONNECTION  5. EMITTER  6. BASE  7. COLLECTOR  8. COLLECTOR  9. BASE  10. EMITTER  11. NO CONNECTION  12. EMITTER  13. BASE  14. COLLECTOR  15. EMITTER  16. COLLECTOR</p>	<p><b>STYLE 2:</b></p> <p>PIN 1. CATHODE  2. ANODE  3. NO CONNECTION  4. CATHODE  5. CATHODE  6. NO CONNECTION  7. ANODE  8. CATHODE  9. CATHODE  10. ANODE  11. NO CONNECTION  12. CATHODE  13. CATHODE  14. NO CONNECTION  15. ANODE  16. CATHODE</p>	<p><b>STYLE 3:</b></p> <p>PIN 1. COLLECTOR, DYE #1  2. BASE, #1  3. EMITTER, #1  4. COLLECTOR, #1  5. COLLECTOR, #2  6. BASE, #2  7. EMITTER, #2  8. COLLECTOR, #2  9. COLLECTOR, #3  10. BASE, #3  11. EMITTER, #3  12. COLLECTOR, #3  13. COLLECTOR, #4  14. BASE, #4  15. EMITTER, #4  16. COLLECTOR, #4</p>	<p><b>STYLE 4:</b></p> <p>PIN 1. COLLECTOR, DYE #1  2. COLLECTOR, #1  3. COLLECTOR, #2  4. COLLECTOR, #2  5. COLLECTOR, #3  6. COLLECTOR, #3  7. COLLECTOR, #4  8. COLLECTOR, #4  9. BASE, #4  10. EMITTER, #4  11. BASE, #3  12. EMITTER, #3  13. BASE, #2  14. EMITTER, #2  15. BASE, #1  16. EMITTER, #1</p>
<p><b>STYLE 5:</b></p> <p>PIN 1. DRAIN, DYE #1  2. DRAIN, #1  3. DRAIN, #2  4. DRAIN, #2  5. DRAIN, #3  6. DRAIN, #3  7. DRAIN, #4  8. DRAIN, #4  9. GATE, #4  10. SOURCE, #4  11. GATE, #3  12. SOURCE, #3  13. GATE, #2  14. SOURCE, #2  15. GATE, #1  16. SOURCE, #1</p>	<p><b>STYLE 6:</b></p> <p>PIN 1. CATHODE  2. CATHODE  3. CATHODE  4. CATHODE  5. CATHODE  6. CATHODE  7. CATHODE  8. CATHODE  9. ANODE  10. ANODE  11. ANODE  12. ANODE  13. ANODE  14. ANODE  15. ANODE  16. ANODE</p>	<p><b>STYLE 7:</b></p> <p>PIN 1. SOURCE N-CH  2. COMMON DRAIN (OUTPUT)  3. COMMON DRAIN (OUTPUT)  4. GATE P-CH  5. COMMON DRAIN (OUTPUT)  6. COMMON DRAIN (OUTPUT)  7. COMMON DRAIN (OUTPUT)  8. SOURCE P-CH  9. SOURCE P-CH  10. COMMON DRAIN (OUTPUT)  11. COMMON DRAIN (OUTPUT)  12. COMMON DRAIN (OUTPUT)  13. GATE N-CH  14. COMMON DRAIN (OUTPUT)  15. COMMON DRAIN (OUTPUT)  16. SOURCE N-CH</p>	

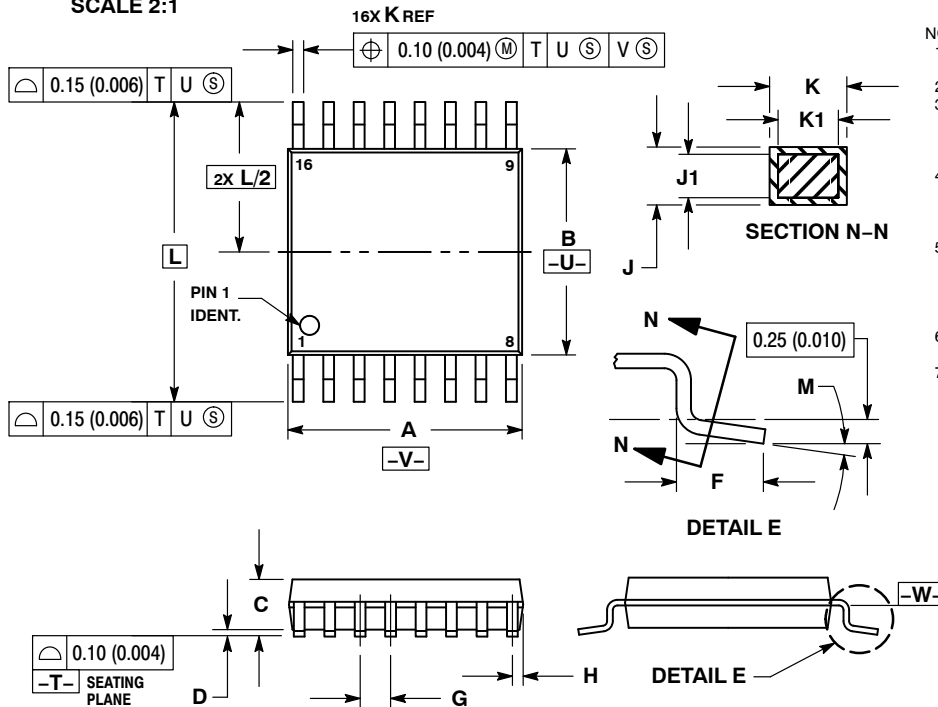
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TSSOP-16 WB  
CASE 948F  
ISSUE B

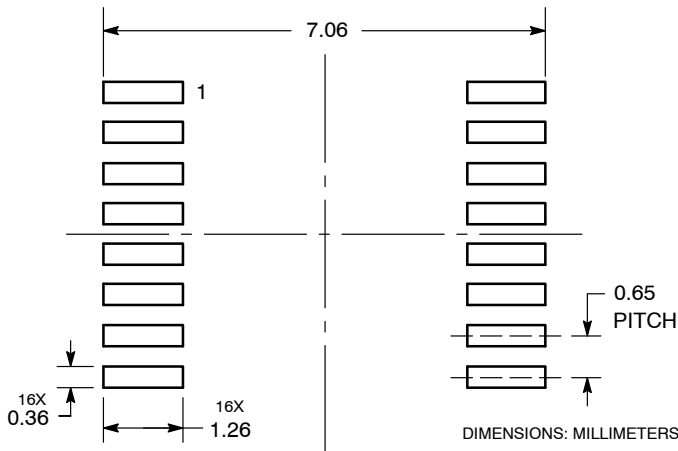
DATE 19 OCT 2006



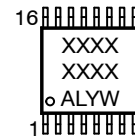
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

RECOMMENDED  
SOLDERING FOOTPRINT\*



GENERIC  
MARKING DIAGRAM\*



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- G or ■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	TSSOP-16	PAGE 1 OF 1

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